# LabAdviser update: 17/8 2021

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| Updated Subject | Contributor | Link to the updated pages |
| TemescalDeposition parameters that influence the oxygen content in Al deposited films. | **Evgeniy Shkondin @Nanolab** | [/Deposition\_of\_Aluminium/Notes\_on\_low\_oxygen\_content\_in\_e-beam\_prepared\_Al\_thin\_films](http://labadviser.nanolab.dtu.dk/index.php/Specific_Process_Knowledge/Thin_film_deposition/Deposition_of_Aluminium/Notes_on_low_oxygen_content_in_e-beam_prepared_Al_thin_films) |
| **Sputter-system Metal oxide**  New page on Reactive sputtered SiO2 | **Evgeniy Shkondin @Nanolab**  **Narwan Kabir Noori @Photonics** | [/Thin\_film\_deposition/Deposition\_of\_Silicon\_Oxide/Reactively\_sputtered\_SiO2\_in\_Sputter-System\_Metal\_Oxide\_(PC1)](http://labadviser.nanolab.dtu.dk/index.php/Specific_Process_Knowledge/Thin_film_deposition/Deposition_of_Silicon_Oxide/Reactively_sputtered_SiO2_in_Sputter-System_Metal_Oxide_(PC1)) |
| **DRIE Pegasus 4**  SiO2 etch on 6” wafers with DUV resist mask on Pegasus 4 | **Berit Herstrøm @Nanolab** | [/Pegasus-4/SiO2\_Etch](http://labadviser.nanolab.dtu.dk/index.php/Specific_Process_Knowledge/Etch/DRIE-Pegasus/Pegasus-4/SiO2_Etch)  [/Pegasus-4/SiO2\_Etch/SiO2\_etch\_with\_resist\_mask](http://labadviser.nanolab.dtu.dk/index.php/Specific_Process_Knowledge/Etch/DRIE-Pegasus/Pegasus-4/SiO2_Etch/SiO2_etch_with_resist_mask) |
| **Etch rate of PECVD nitride in the ASE**  With the recipe 1SiO2ICP1. | **Emil Christian Stillhoff Jensen @Nanolab** | [/Etch/Etching\_of\_Silicon\_Oxide/SiO2\_etch\_using\_ASE#SiO2\_etch\_with\_resist\_mask\_on\_wafer\_with\_clamping\_and\_He\_backside\_cooling](http://labadviser.nanolab.dtu.dk/index.php/Specific_Process_Knowledge/Etch/Etching_of_Silicon_Oxide/SiO2_etch_using_ASE#SiO2_etch_with_resist_mask_on_wafer_with_clamping_and_He_backside_cooling) |
| **Thermal Evaporator**  Thermal evaporation of Cr | **Evgeniy Shkondin @Nanolab** | [Thin\_film\_deposition/Deposition\_of\_Chromium/Thermal\_evaporation\_of\_Cr\_in\_Thermal\_evaporator](http://labadviser.nanolab.dtu.dk/index.php/Specific_Process_Knowledge/Thin_film_deposition/Deposition_of_Chromium/Thermal_evaporation_of_Cr_in_Thermal_evaporator) |
| **New optical profiler (Sensofar)**  Installed in February | **Berit G. Herstrøm @Nanolab** | [Characterization/Profiler#Optical\_Profiler\_.28Sensofar\_S\_Neox.29](http://labadviser.nanolab.dtu.dk/index.php/Specific_Process_Knowledge/Characterization/Profiler#Optical_Profiler_.28Sensofar_S_Neox.29) |
| **RTP Jipelec 2**  New system installed in January | **Pernille V. Larsen @Nanolab** | [/Thermal\_Process/RTP\_Jipelec\_2](http://labadviser.nanolab.dtu.dk/index.php/Specific_Process_Knowledge/Thermal_Process/RTP_Jipelec_2) |
| **Aligner: Maskless 03 (from November)**  Updated process parameters for AZ5214E  Correction of "accessible stage coordinates" | **Jens H. Hemmingsen @Nanolab** | [Lithography/Aligners/Aligner:\_Maskless\_03\_processing#Process\_Parameters](http://labadviser.nanolab.dtu.dk/index.php/Specific_Process_Knowledge/Lithography/Aligners/Aligner:_Maskless_03_processing#Process_Parameters)  [Lithography/Aligners/Aligner:\_Maskless\_03\_processing#Top\_Side\_Alignment](http://labadviser.nanolab.dtu.dk/index.php/Specific_Process_Knowledge/Lithography/Aligners/Aligner:_Maskless_03_processing#Top_Side_Alignment) |
| **The Dry Etch TPT**  The Dry Etch Tool Package Training Course has been implemented in DTU Learn. See more information on the home page <https://www.nanolab.dtu.dk/use-nanolab/tpt/The-dry-etch-tool-package-training-TPT->  and in LabAdviser | **Berit Herstrøm @Nanolab** | [Courses/TPT\_Dry\_Etch](http://labadviser.nanolab.dtu.dk/index.php/LabAdviser/Courses/TPT_Dry_Etch) |

# Equipment Manuals updated in LabManager (since 1nst of June):

As an approved user on a piece of equipment you have to make sure you have read and understood the latest version of the manual before using the equipment.

Manual for DRIE-Pegasus 3 and 4, ver 1.2

User manual for E-Beam writer JEOL JBX-9500FS, ver 2.2

Manual for Spin coater: RCD8, ver 1.4

Manual for Hotplate (SU8), ver 3.4

Manual for Furnace: Multipurpose Annealing, ver 3

Manual for ellipsometer M-2000V, ver 2.5

Manual for Plasma Asher1\_Model 300 Plasma Processor, ver 5.3

Manual for Inclined UV-lamp, ver 3.2

Manual for Oven 110-250C, ver 3.2

Manual for Oven 90C, ver 3.2

Manual for Gate Oxide furnace (A2), ver 7

Manual for Developer: E-beam, ver 1.4